

/ Descriptions

WR0553 M M $\approx 9^\circ$ II 1

Schottky Barrier Diode in a TO-220 Plastic Package.

/ Features

$H^* b \pi$ I H I $\alpha^\circ \Omega$ I $\tilde{\omega}$ I

Low forward voltage drop, low power losses, High efficiency operation.

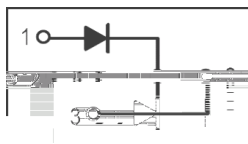
/ Applications

$\tilde{\omega} \tilde{\omega}$ I $\psi \pi$ I $\tilde{\omega} \pi \diamond$ I $\pi \tilde{\omega}$ II 1 I RU0Iqj $\sim$ II 1 I GF0GF $^\circ \Omega \pi \approx \diamond - \pi b 3 \tilde{\omega}$

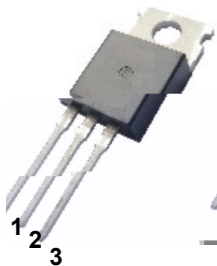
For use in high frequency inverters, switching power supplies, freewheeling diodes,

OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 χ Anode

PIN 2 χ Cathode

PIN 3 χ Anode

/ h_{FE} Classifications & Marking

M 1 " See Marking Instructions.

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Reverse Voltage	V_{RMS}	105	V
Average Rectified Forward Current	$I_{F(AV)}$	2×10	A
Non Repetitive Peak Surge Current	I_{FSM}	120	A
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.8	$^{\circ}\text{C/W}$
Junction and Storage Temperature Range	T_j T_{stg}	-55 +150	

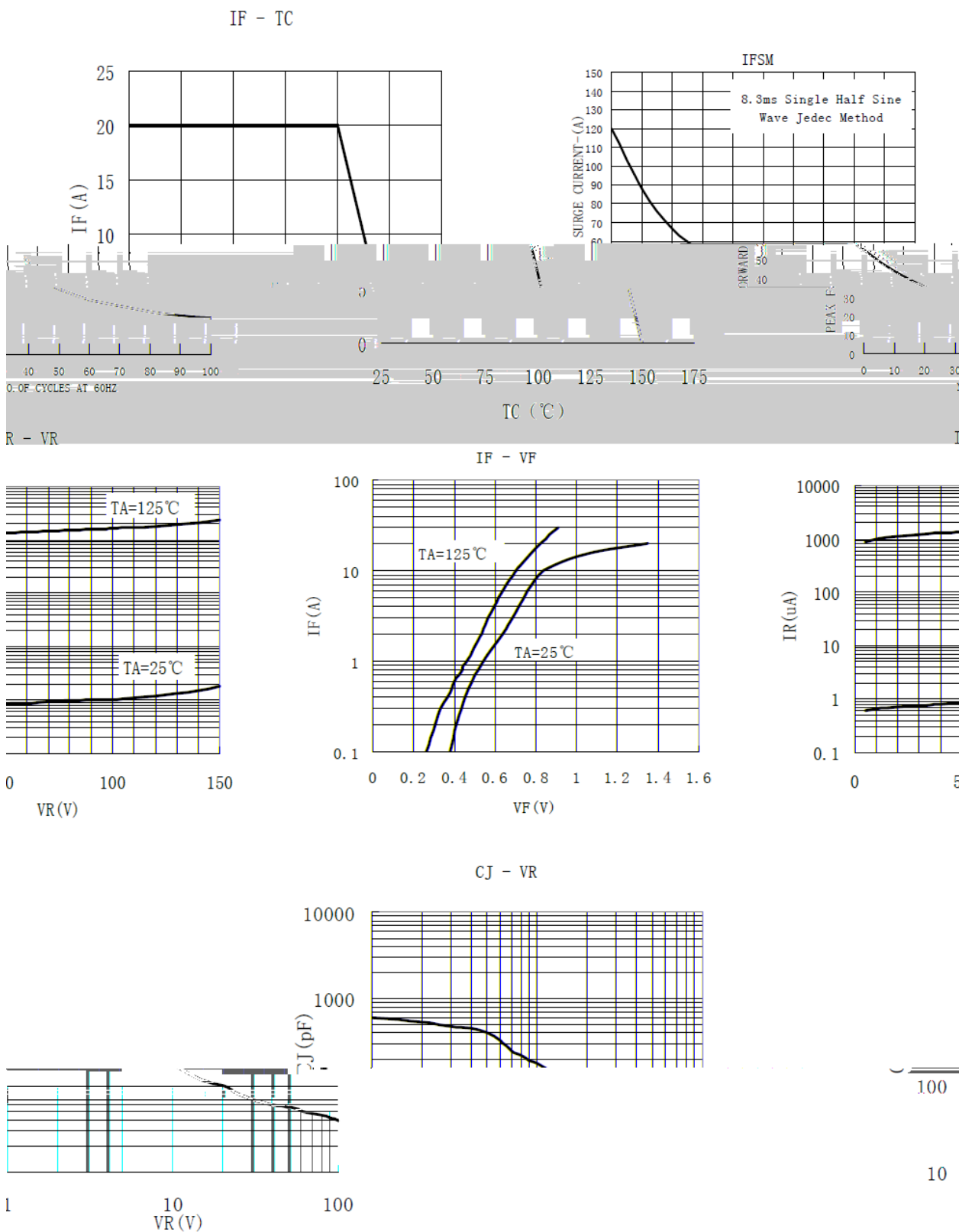
/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Reverse Voltage	V_{BR}	$I_R=1\text{mA}(T_a=25^\circ\text{C})$	150			V
Forward Voltage	V_F	$I_F=5\text{A}(T_a=25^\circ\text{C})$		0.74		V
		$I_F=10\text{A}(T_a=25^\circ\text{C})$		0.84	0.95	V
		$I_F=5\text{A}(T_a=125^\circ\text{C})$		0.59		V
		$I_F=10\text{A}(T_a=125^\circ\text{C})$		0.69	0.75	V
Instantaneous Reverse Current	I_R Note 1	$V_R=150\text{V}(T_a=25^\circ\text{C})$			50	μA
		$V_R=150\text{V}(T_a=125^\circ\text{C})$		3	10	mA

/Notes

- Short duration pulse test used to minimize self-heating effect.
- Unless otherwise noted, values for the parameters of a single chip

/ **Electrical Characteristic Curve**

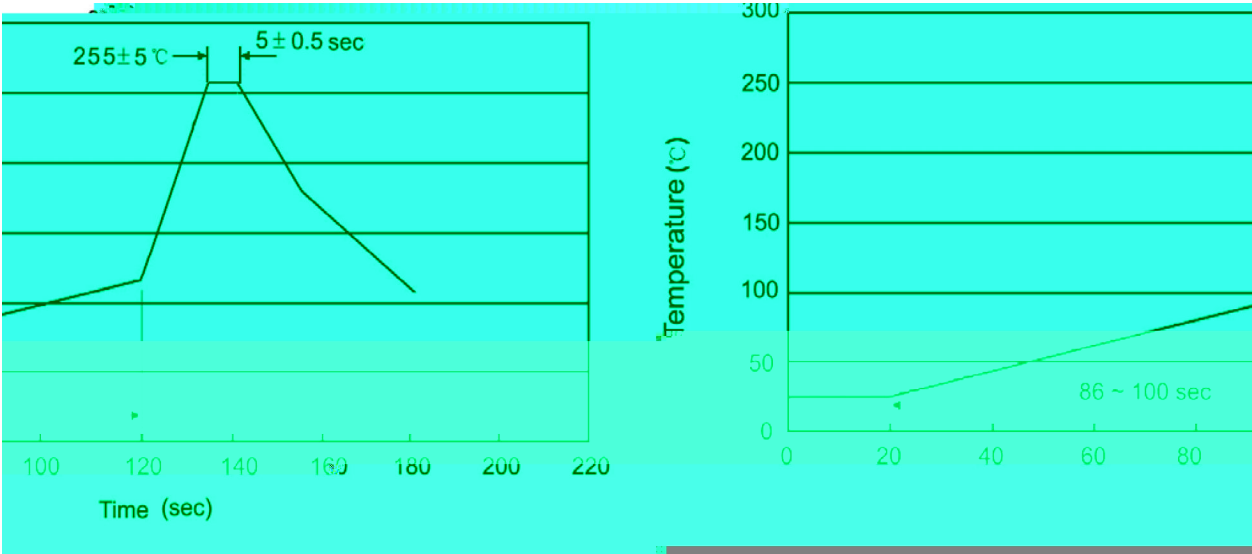


T0-220

单位: 



() / Temperature Profile for Dip Soldering(Pb-Free)



1. Preheating: 25~150 °C, Time: 60~90sec;
2. Peak Temp.: 255±5 °C, Duration: 5±0.5sec;
3. Cooling Speed: 2~10 °C/sec.

- Note:
1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255±5 °C, Duration: 5±0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

□ 270±5 °C, Time: 10±1 sec. Temp.: 270±5 Time: 10±1 sec

/ Packaging SPEC.

“Q” / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

“1” / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只套管	套管盒	只盒	盒箱	只箱	套管	盒	箱

/ Notices